國立清華大學電機資訊學院

116學年度國際半導體暨IC設計產業人才專班申請表

College of Electrical Engineering and Computer Science
National Tsing Hua University
Application Form for International Semiconductor and IC Design Program 2027

I. Personal Information 申請人資料	Photo 照片
Applicant No. 申請件編號：(office use only)	
English Name 英文姓名 (as in passport) Family Name: Given Name:	
Chinese Name 中文姓名 (optional)	

Contact Email 郵件帳號	**Date of Birth** 生日 (year/month/date)
Country of Birth 出生地	**Nationality** 國籍
Passport Number 護照號碼 (If applicable)	Biological Gender 性別： M(男) F(女)

Contact Information 聯絡資料

Address 戶籍地址

Street 街道:
City 城市:
Country 國家:
Zip code 郵遞區號:

E-mail 電子信箱:

Contact Phone/Mobile Phone 電話: (country code)+(phone number)

Emergency Contact 緊急聯絡人

Name 姓名: Relationship 關係:
Phone 電話:
Email 電子信箱:
Address 地址:

II. Family Background 家庭背景

Father	
English Name 英文姓名：	
Chinese Name 中文姓名：(if applicable)	
Nationality 國籍：	
Country of Residence 居住國：	
Phone 電話：	E-mail：
Mother	
English Name 英文姓名：	
Chinese Name 中文姓名：(if applicable)	
Nationality 國籍：	
Country of Residence 居住國：	
Phone 電話：	E-mail：

III. Education Background 教育背景

Highest Degree Received

Name of Institution 學校名稱:

Major in 系所:

School Address 學校地址

Street:

City: State/ Province:

Postal/ Zip Code: Country:

Date of Graduation 畢業年月: (MM-DD-YYYY)

Average GPA: _____ of _____ Average Class Ranking: _____

Additional Degree Received

School Name 學校名稱:

Department or Focused Area 系所或專業領域:

School Address 學校地址

Street:

City: State/ Province:

Postal/ Zip Code: Country:

Date of Graduation 畢業年月: (MM-DD-YYYY)

Average GPA: _____ of _____ Average Class Ranking: _____

Others

School Name 學校名稱:

Department or Focused Area 系所或專業領域:

School Address 學校地址

Street:

City: State/ Province:

Postal/ Zip Code: Country:

Date Graduated 畢業年月: (MM-DD-YYYY)

Average GPA: _____ of _____ Average Class Ranking: _____

IV. Mentionable Activity 亮點活動

You may list your mentionable achievements, work experience (if any), and other relevant experiences.

V. Other Information 其他資訊

Language Proficiency 語言能力

English 英文

☐ Fluent 傑出	☐ Good 優秀	☐ Moderate 好	☐ Limited 普通	☐ None 差

Mandarin 中文

☐ Fluent 傑出	☐ Good 優秀	☐ Moderate 好	☐ Limited 普通	☐ None 差

Contact of Advisor 指導教授聯繫

Have you contacted any professors in the program or the College of EECS regarding your future study or research? 你是否曾就未來的學習或研究與本班或本院教授聯繫？ ☐ Yes ☐ No

Has any professor indicated willingness to serve as your future advisor?
是否已有教授表示願意擔任你未來的指導教授？ ☐ Yes ☐ No

If yes from any of the above, please provide the professor's name below, and include the correspondence records as one of the supporting documents:

Professor's Name 教授姓名:

Department/Institute 系別:

E-mail 電子郵件:

(*Please note that contacting a professor or obtaining a professor's willingness to serve as your advisor prior to admission may be taken into consideration during the application review process, but is not required and does not guarantee admission.*)

VI. Contacts for Recommendation Letters

Referee 推薦人 1	
Name 姓名:	
Current Position/Job Title 現職名稱:	
Current Employer 現職單位:	
E-mail 電子郵件:	
Relationship with the applicant 與申請人之關係:	
Referee 推薦人 2	
Name 姓名:	
Current Position/Job Title 現職名稱:	
Current Employer 現職單位:	
E-mail 電子郵件:	
Relationship with the applicant與申請人之關係:	

VII. Scholarship & Sponsorship Options

The ISICP students are eligible for the Industry-Academia Scholarship provided by Taiwan's Ministry of Education (MOE), along with a monthly living allowance sponsored by our industrial partners. Three sponsorship options are available for the 2027 intake. Please review the obligations of each option carefully, as your selection may affect the admission process and post-graduation benefits.

☐ TSMC (Taiwan Semiconductor Manufacturing Co., Ltd.) Sponsorship.

☐ TSC (TOPCO SCIENTIFIC Co., Ltd) Sponsorship

☐ TSC First Choice / TSMC Alternative
I would apply for the TSC sponsorship first. If I am not selected through the industry interview, I would like to receive TSMC Sponsorship and seek employment independently after graduation, in accordance with the agreement.

Click here for details about each sponsorship option. The same information is available on the ISICP admission webpage.

Declaration: ☐ I have read and understood the obligations of each sponsorship option and agree to comply with the applicable agreement if admitted and enrolled in the program.

VIII. Statement of Purpose 學習計畫書

Statement of Purpose

Study Plan

(Please hit enter to add more pages as needed.)

國立清華大學電機資訊學院

115學年度國際半導體暨IC設計產業人才專班申請表

College of Electrical Engineering and Computer Science
National Tsing Hua University
Application Form for International Semiconductor and IC Design Program 2026

Application Checking List

Application Number: (office use only)

Applicant:

Nationality:

NOTE Please have the outgoing exchange program coordinator at your home institution to check your required documents and complete the following session I and II.

Section I Application Package		**List of General Required Documents**
	☐	**Application Form with Statement of Purpose**
	☐	An official copy of the **Transcript** (English)
	☐	A copy of your highest **Degree Diploma**
	☐	**Recommendation Letters** (Referees' Contacts)
	☐	**Language Certificate** ☐ English Proficiency Test ☐ Chinese Proficiency Test
	☐	A Copy of **Passport Identity page** (valid for at least 3 months) or nationality verification
	☐	**Financial Certificate**
	☐	**Declaration Form**

Section II Applicant's Statement	**Certification**
	I certify that the information I have provided in this application is complete and correct. I understand that any misrepresentation, omission, or submission of false information is grounds for rejection of my application, withdrawal of acceptance, cancellation of enrollment, and/or disciplinary action at a future date. If my application is accepted, I agree to abide by the policies, rules, and regulations of the Republic of China and National Tsing Hua University.
	Applicant's Signature (簽名)：_____ **Date:**